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## **Kulicke & Soffa Continues to Gain Traction with its Advanced Packaging Solutions**

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), continues to expand its presence in the advanced packaging market, through focused feature development and strategic customer engagement.

K&S has a complete offering of advanced packaging solutions supporting Fan-Out Wafer Level Packaging (FOWLP), Wafer Level Packaging (WLP), Flip Chip, System-in-Package (SiP), Package-on-Package (PoP), Embedded Die and Thermo-Compression Bonding (TCB).

Continuing from the first market acceptance of its APAMA™ solutions in February this year, K&S recently received a third purchase order from a global memory manufacturer. In addition, K&S has shipped more than 60 sets of its HYBRID equipment, a multi-application advanced packaging solution, to a major assembly and test provider supporting premium smartphone SIP applications.

Tong Liang Cheam, Kulicke & Soffa's Vice President of the Advanced Packaging Business Line and Corporate Strategy, commented, "Over the past several years we have aggressively expanded our market presence which now collectively addresses every high-growth advanced packaging process. The recent market successes serve as a testament to our unwavering dedication to support and resolve our customers' most challenging interconnect requirements."

K&S continues to further its advanced packaging program through ongoing evaluations, qualifications and its global sampling program with leading integrated device manufacturers and assembly and test providers.

### **About Kulicke & Soffa**

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. ([www.kns.com](http://www.kns.com))

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